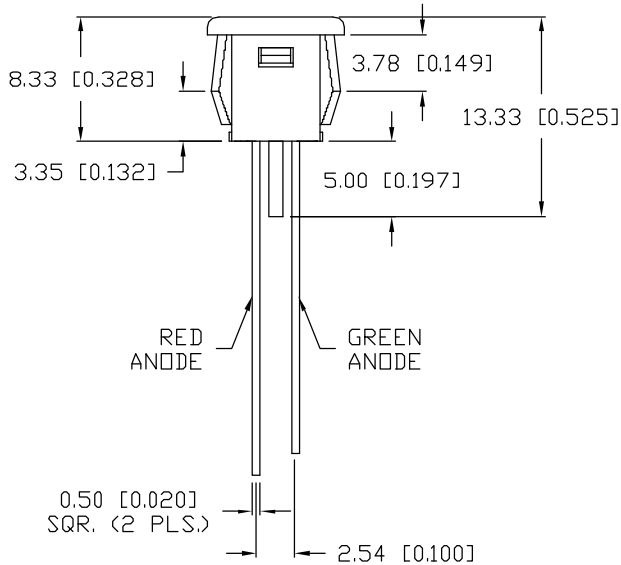
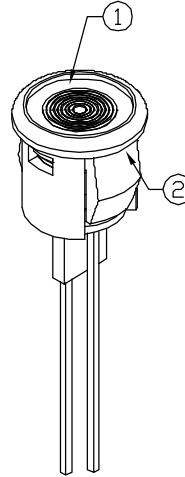
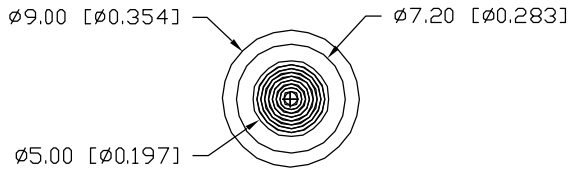


UNCONTROLLED DOCUMENT

PART NUMBER		REV.
SSI-LXH387HGW		A
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10BRDR. & REDRAWN.	8.2.01



RED ANODE  
GREEN ANODE

0.50 [0.020]  
SQR. (2 PLS.)  
2.54 [0.100]

ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^\circ\text{C}$   $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		700 (RED)		nm	
		565 (GREEN)		nm	
FORWARD VOLTAGE (R/G)		2.0/2.2	2.5/2.6	$V_f$	
REVERSE VOLTAGE	5.0			$V_r$	$I_r=100\mu\text{A}$
AXIAL INTENSITY (R/G)		4/10		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		120		$2x$ theta	
EMITTED COLOR:	RED/GREEN				
EPOXY LENS FINISH:	MILKY WHITE DIFFUSED				

LIMITS OF SAFE OPERATION AT  $25^\circ\text{C}$

PARAMETER	COLORS	MAX	UNITS
PEAK FORWARD CURRENT*		150	mA
STEADY CURRENT		25	mA
POWER DISSIPATION	(R/G)	120/105	mW
DERATE FROM $25^\circ\text{C}$		-1.2	$\text{mW}/^\circ\text{C}$
OPERATING, STORAGE TEMP.		-40 TO +85	$^\circ\text{C}$
SOLDERING TEMP.		+260	$^\circ\text{C}$
2.0mm FROM BODY			3 SEC. MAX

\*  $t < 10\mu\text{s}$

NOTES:

- SSL-LX433HGW LED.
- HOLDER: LXP-SSI-387BSH, LXP-SSI-387BZL.
- PANEL HOLE CUT OUT: 5/16" DIAMETER.

UNCONTROLLED DOCUMENT

\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN= +DECIMAL PRECISION MAX.= +0.00 -DECIMAL PRECISION

REV. A	PART NUMBER SSI-LXH387HGW	CONFIDENTIAL INFORMATION THE INFORMATION CONTAINED IN THIS DOCUMENT IS THE PROPERTY OF LUMEX INC. EXCEPT AS SPECIFICALLY AUTHORIZED IN WRITING BY LUMEX INC., THE HOLDER OF THIS DOCUMENT SHALL KEEP ALL INFORMATION CONTAINED HEREIN CONFIDENTIAL AND SHALL PROTECT SAME IN WHOLE OR IN PART FROM DISCLOSURE AND DISSEMINATION TO ALL THIRD PARTIES.	290 E. HELEN ROAD PALATINE, IL 60067-6976 PHONE: +1.847.359.2790 US WEB: www.lumex.com TW WEB: www.lumex.com.tw
T-5 FRESNEL LENS PANEL MOUNT INDICATOR, BICOLOR 700nm RED/565nm GREEN LED, MILKY WHITE DIFFUSED LENS.		RELIABILITY NOTE OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.	DRAWN BY: CT CHECKED BY: APPROVED BY: DATE: 8.2.01 PAGE: 1 OF 1 SCALE: N/A